Materials Declaration Form

IPC	1752	**Version**	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2023-04-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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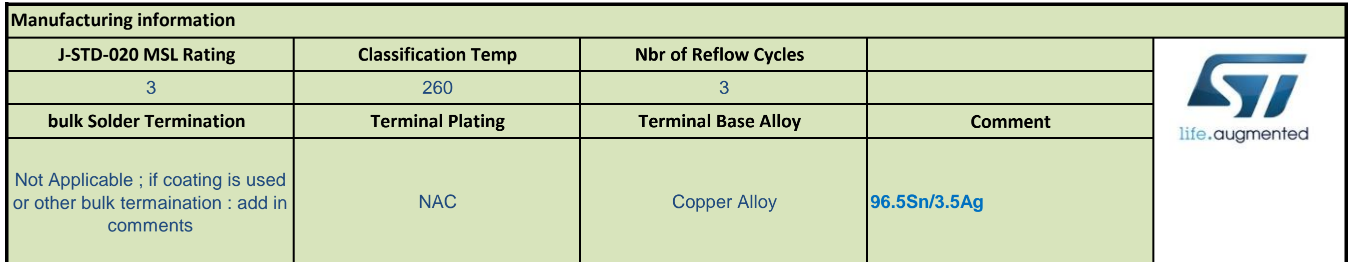
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32WL55JCI7	E0JB*497XXXY	A	9991	2023-04-05
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	30.85	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	NAC	Copper Alloy	**96.5Sn/3.5Ag**	

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BGA	5x5	73	bulk solder	
Comment	Package : B08E UFBGA 5X5X0.6 73L P0.5 9X9 DM00488486			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-10 Jun 2022	
Query	Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E0JB*497XXXY				6000000.0	1000000.3
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	2.288	mg	supplier	die	Silicon (Si)	7440-21-3		1.843	mg	805507	59743
				supplier	metallization	Aluminium (Al)	7429-90-5		0.021	mg	9178	681
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	82168	6094
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	437	32
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.061	mg	26661	1977
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	874	65
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	874	65
				supplier	Passivation	Silicon Nitride	12033-89-5		0.048	mg	20979	1556
				supplier	Passivation	Silicon Oxide	7631-86-9		0.122	mg	53322	3955
Substrate (A265590)	M-011 Other inorganic materials	9.963	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		0.598	mg	60000	19378
				supplier	BT-substrate	Glass cloth	65997-17-3		3.696	mg	371000	119818
				supplier	BT-substrate	Copper foil	7440-50-8		4.553	mg	457000	147593
				supplier	Solder mask	2-benzyl-2-dimethylamino-4-morpholinobutyro	119313-12-1		0.354	mg	35500	11465
				supplier	Solder mask	Propanol, 1(or 2)-(2-methoxymethylethoxy)-	34590-94-8		0.364	mg	36500	11788
				supplier	Solder mask	Solvent naphtha (petroleum), heavy arom.	64742-94-5		0.334	mg	33500	10819
				supplier	Solder mask	Copper,[29H,31H-phthalocyaninato(2-)-.kappa.	147-14-8		0.065	mg	6500	2099
DAF (ATB-125)	M-011 Other inorganic materials	3.345	mg	supplier	film	Butadiene, acrylonitrile polymer, carboxy-termi	68610-41-3		2.296	mg	686250	74411
				supplier	film	Formaldehyde, polymer with (chloromethyl)oxi	37382-79-9		0.859	mg	256850	27851
				supplier	film	Dapsone	80-08-0		0.123	mg	36900	4001
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.033	mg	10000	1084
				supplier	film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.033	mg	10000	1084
Bonding wire (Au)	Precious metals	0.273	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.273	mg	1000000	8850
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	13.205	mg	supplier	Molding Compound	Epoxy resin	Proprietary		0.528	mg	40000	17122
				supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		11.885	mg	900000	385247
				supplier	Molding Compound	Phenol resin	Proprietary		0.739	mg	56000	23971
				supplier	Molding Compound	Carbon Black	1333-86-4		0.053	mg	4000	1712
Solder balls (96.5Sn/3.5Ag)	Solder	1.775	mg	supplier	Solder	Tin (Sn)	7440-31-5		1.712	mg	964500	55496
				supplier	Solder	Silver(Ag)	7440-22-4		0.063	mg	35500	2043